Innovative **Technology**
for a **Connected** World

# Sil25-RXP
# Form-In-Place

* does not represent actual color

## Sil25-RXP Form-In-Place

### A single component, non-slump, high flexibility, room temperature silicone gasket material.

Laird Technologies’ Form-In-Place is an automated system for dispensing non-conductive and conductive elastomer EMI shielding and grounding gaskets onto metal substrates. This product is particularly ideal for base stations, PDAs, PC cards, radios, and mobile phones, as well as many other cast enclosures and packaged electronic assemblies.

## TYPICAL VALUES

| MATERIAL PROPERTIES | TEST METHOD | Sil25-HXP |
|---|---|---|
| Product Type | | Single Component Silicone |
| Color | | White |
| Density, g/cm$^3$ | | 1.2 |
| Hardness, Shore A | | 25 |
| Tensile Strength, MPa | ASTM D412 | 4.5 |
| Compression Set, 22 Hrs, 23°C, 25% Compression | ASTM D575 | <20 |
| Adhesion (Al), N/cm$^2$ | LT-FIP-CLE-03 | 220 |
| Time to skin @ 23°C, 50% RH | | 10 – 25 minutes |
| Cure @ 23°C, 50% RH | | 12 hours per mm thick |

Information on the product described is based on laboratory test data which Laird Technologies believes to be reliable. It is recommended that each user make their own tests to determine the suitability of Laird Technologies’ products for their application.

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